This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A method for curing or drying of a surface-coating layer or of a printing ink, comprising adding to a ~~the~~ surface-coating composition ~~layer~~ or ~~the~~ printing ink in an amount of 0.1-4 % by weight based on the surface-coating composition or the printing ink one or more pale or transparent particulate semiconductor materials or one or more particulate substrates coated with one or more pale or transparent semiconductor materials, applying to a surface the ink or the surface-coating composition to form a surface-coating layer and curing or drying the surface-coating layer or ink.

2. (Previously Presented) A method according to Claim 1, wherein the one or more pale or transparent particulate semiconductor materials are homogeneous in structure or the one or more pale or transparent semiconductor materials are applied as a coating to a particulate substrate.

3. (Previously Presented) A method according to Claim 1, wherein the particulate semiconductor materials or the particulate substrates are spherical, flake-form or needle-shaped.

4. (Previously Presented) A method according to Claim 1, wherein the semiconductor material is built up oxidically or sulfidically.

5. (Previously Presented) A method according to Claim 1, wherein the semiconductor material is built up on the basis of indium oxide, antimony oxide, tin oxide, zinc oxide, zinc sulfide, tin sulfide or is a mixture of the said materials.

6. (Previously Presented) A method according to Claim 5, wherein the mixture is indium-tin oxide (ITO).

7. (Previously Presented) A method according to Claim 1, wherein the

substrate is selected from the group consisting of mica flakes, SiO_2 flakes, Al_2O_3 flakes, glass flakes, aluminium flakes, BiOCl flakes, SiO_2 spheres, glass spheres, hollow glass spheres, TiO_2 spheres, polymer spheres, TiO_2 needles and mixtures thereof.

8. (Previously Presented) A method according to Claim 1, wherein the semiconductor materials are doped.

9. (Previously Presented) A method according to Claim 1, wherein the semiconductor has an amorphous, crystalline or microcrystalline structure.

10. (Cancelled)

11. (Currently Amended) A surface coating or printing ink composition, comprising in an amount of 0.1-4 % by weight based on the coating or printing ink composition one or more pale or transparent particulate semiconductor materials or particulate substrates coated with pale or transparent semiconductor materials and one or more carriers to form the surface coating or printing ink composition ~~a curing or drying additive composition according to Claim 10~~.

12. (Previously Presented) A curing or drying additive composition according to claim 10, consisting essentially of one or more pale or transparent particulate semiconductor materials or particulate substrates coated with pale or transparent semiconductor materials.

13. (Previously Presented) A method according to claim 1, further comprising physically drying in air or curing by oxidation, condensation, thermally, or by IR irradiation the surface-coating layer or the printing ink.

14. (Previously Presented) A method according to claim 1, wherein the coating layer is an automobile paint.

15. (Previously Presented) A method according to claim 1, wherein the

curing or drying of a surface-coating layer is achieved.

16. (Previously Presented) A method according to claim 1, wherein the curing or drying of a printing ink is achieved.

17. (Currently Amended) A method according to claim 1, which is for shortening the curing and/or drying time of a surface-coating layer or printing ink, ~~by about 10-60% of the drying time without the addition of one or more pale or transparent particulate semiconductor materials or one or more particulate substrates coated with one or more pale or transparent semiconductor materials~~ comprising adding to a ~~the~~ surface-coating composition ~~layer~~ or the printing ink in an amount of 0.1-4 % by weight based on the surface-coating composition or the printing ink one or more pale or transparent particulate semiconductor materials or one or more particulate substrates coated with one or more pale or transparent semiconductor materials to shorten the curing or drying time of the surface-coating layer or printing ink by about 10-60% in comparison to the curing or drying time of the surface-coating layer or printing ink without the one or more pale or transparent particulate semiconductor materials or one or more particulate substrates coated with one or more pale or transparent semiconductor materials, applying to a surface the ink or the surface-coating composition to form a surface-coating layer and curing or drying the surface-coating layer or ink.

18. (Previously Presented) A method according to claim 17, wherein the printing ink or surface-coating layer cures or dries by IR radiation.

19. (Previously Presented) A method according to claim 17, wherein the curing or drying of a surface-coating layer is achieved.

20. (Previously Presented) A method according to claim 17, wherein the curing or drying of a printing ink is achieved.

21. (New) A method for curing or drying of a surface-coating layer or of a printing ink, comprising applying to a surface an ink or a surface-coating composition to

form a surface-coating layer and curing or drying the surface-coating layer or ink, wherein to the surface-coating composition or printing ink in an amount of 0.1-4 % by weight based on the surface-coating composition or the printing ink one or more pale or transparent particulate semiconductor materials or one or more particulate substrates coated with one or more pale or transparent semiconductor materials have been added.